



SMD Photovoltaic Solar Cell Protection Schottky Rectifier



FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Guardring for overvoltage protection
- Low forward voltage drop, low power losses
- High efficiency
- Low thermal resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT
HALOGEN
FREE

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	12 A
V_{RRM}	40 V
I_{FSM}	280 A
E_{AS}	20 mJ
V_F at $I_F = 12$ A	0.43 V
T_J max.	150 °C

MECHANICAL DATA

Case: TO-277A (SMPC)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test

TYPICAL APPLICATIONS

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	SS12P4S	UNIT
Device marking code		124S	
Maximum repetitive peak reverse voltage	V_{RRM}	40	V
Maximum DC forward current (fig. 1)	I_F	12 ⁽¹⁾ 4.4 ⁽²⁾	A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	280	A
Non-repetitive avalanche energy at $I_{AS} = 2.0$ A, $T_J = 25$ °C	E_{AS}	20	mJ
Operating junction and storage temperature range	T_{OP}, T_{STG}	- 55 to + 150	°C
Junction temperature in DC forward current without reverse bias, $t \leq 1$ h ⁽³⁾	T_J	≤ 200	°C

Notes

- (1) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink
- (2) Free air, mounted on recommended copper pad area
- (3) Meets the requirements of IEC 61215 Ed. 2 bypass diode thermal test

ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 6 A	T _A = 25 °C	V _F ⁽¹⁾	0.43	-	V
	I _F = 12 A			0.50	0.60	
	I _F = 6 A	T _A = 125 °C		0.33	-	
	I _F = 12 A			0.43	0.52	
Reverse current	V _R = 40 V	T _A = 25 °C	I _R ⁽²⁾	100	800	μA
		T _A = 125 °C		50	100	mA
Typical junction capacitance	4.0 V, 1 MHz		C _J	750	-	pF

Notes(1) Pulse test: 300 μs pulse width, 1 % duty cycle(2) Pulse test: Pulse width $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)}$	100	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(2)}$	3	

Notes(1) Free air, mounted on recommended copper pad area. Thermal resistance $R_{\theta JA}$ - junction to ambient.(2) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance $R_{\theta JM}$ - junction to mount.

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SS12P4S-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel
SS12P4S-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel

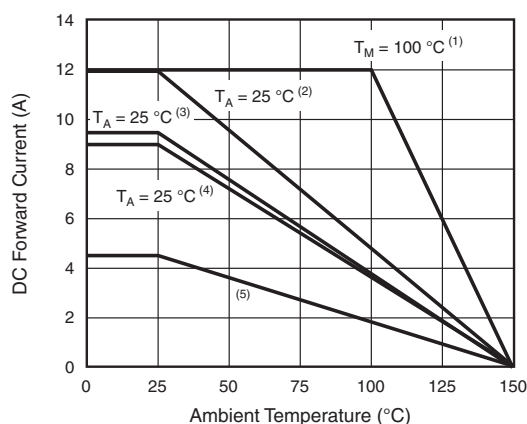
RATINGS AND CHARACTERISTICS CURVES($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Fig. 1 - Maximum Current Derating Curve

Notes

- (1) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink, T_M measured at the terminal of cathode band
- (2) Mounted on 30 mm x 30 mm Al PCB ($R_{\theta JA} = 20\text{ }^{\circ}\text{C/W}$)
- (3) Mounted on 30 mm x 30 mm x 2 copper pad areas FR4 PCB ($R_{\theta JA} = 30\text{ }^{\circ}\text{C/W}$)
- (4) Mounted on 25 mm x 25 mm x 2 copper pad areas FR4 PCB ($R_{\theta JA} = 30\text{ }^{\circ}\text{C/W}$)
- (5) Free air, mounted on recommended copper pad area ($R_{\theta JA} = 100\text{ }^{\circ}\text{C/W}$)

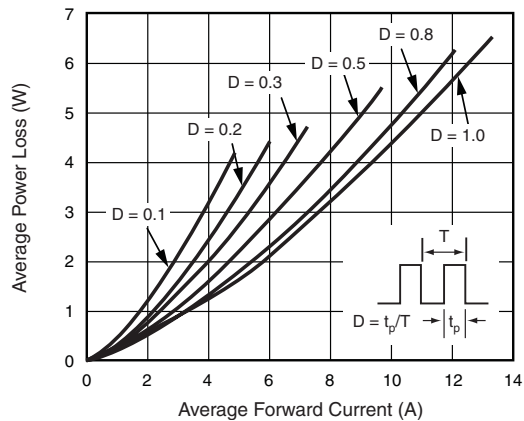


Fig. 2 - Forward Power Loss Characteristics

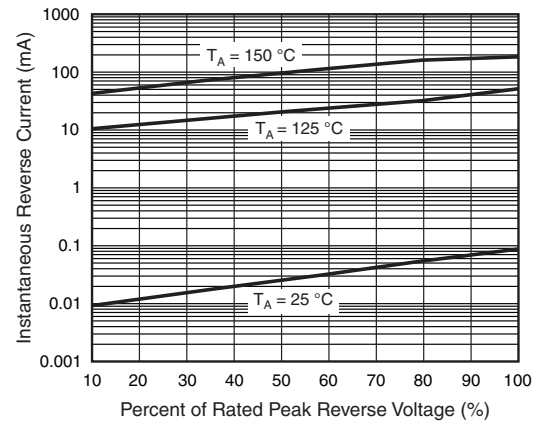


Fig. 4 - Typical Reverse Leakage Characteristics

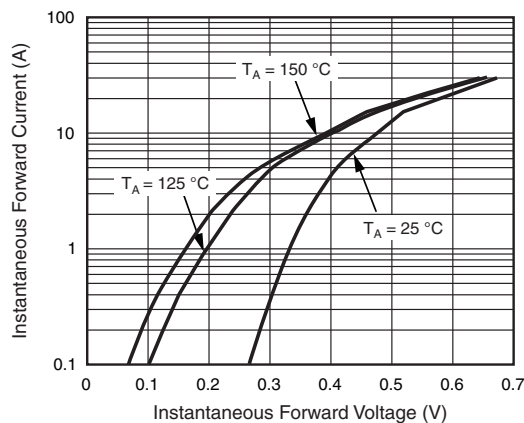


Fig. 3 - Typical Instantaneous Forward Characteristics

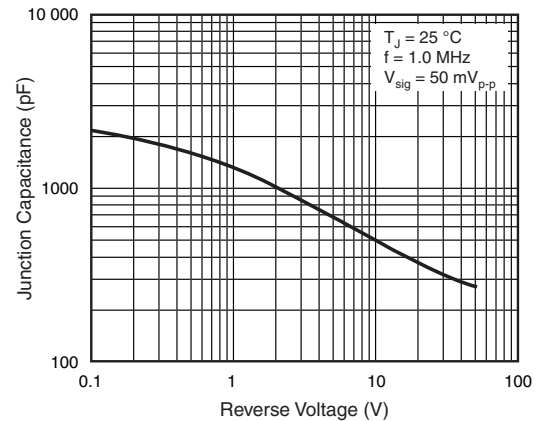
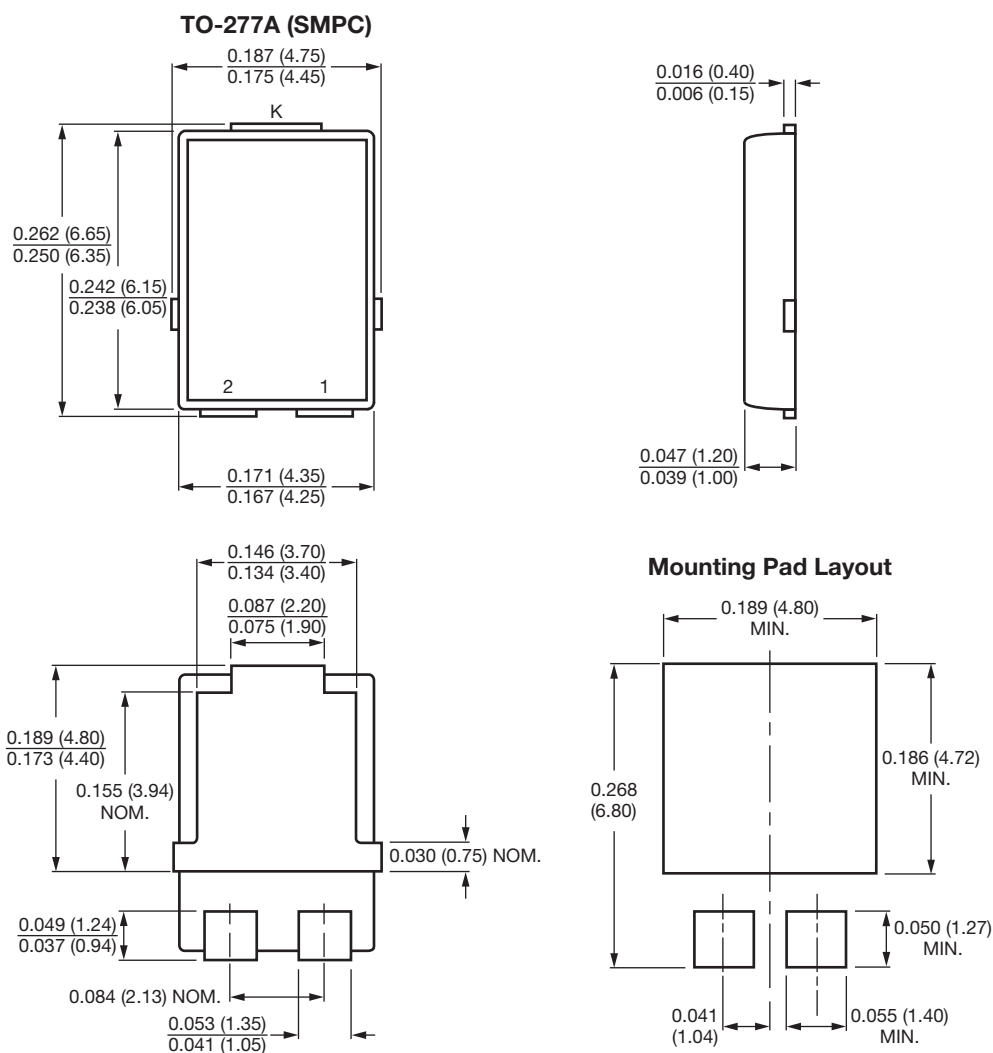


Fig. 5 - Typical Junction Capacitance

SS12P4S

Vishay General Semiconductor

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

Conform to JEDEC TO-277A



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